Notification Number:		20240621003.0		Notification Date:		June 24, 2024	
Title: ECAT symbol update for select devices							
Customer Change Management te			team	Dept:	ept: Quality Services		
Change Type:							
Assembly Site		Desig		Wafer Bump Material			
Assembly Proce	SS	Data Sheet			Wafer Bump Process		
Assembly Mater	ials	Part i	ige	Wafer Fab Site			
Mechanical Spe	cificat	ion Test :		Wafer Fab Materials			
Packing/Shippir	g/Lat	peling Test Process			Wafer Fab Process		
Notification Details							
Description of Change:							
Texas Instruments Incorporated is announcing an information only notification for the ECAT symbol update for devices listed below. Devices will remain at the current assembly site.							
		Current		Proposed			
Topside Symbo	ı	\T/YMLLLLS G 4 TL28L92		\T/YMLLLLS G3 TL28L92			
Decree for Change							
Reason for Change:							
Update the correct ECAT value per device lead finish							
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):							
None							
Changes to product identification resulting from this notification:							
None.							
Product Affected:							
TL28L92FR	TI	_28L92FRR	IFR	TL28L9	92IFRR		

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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